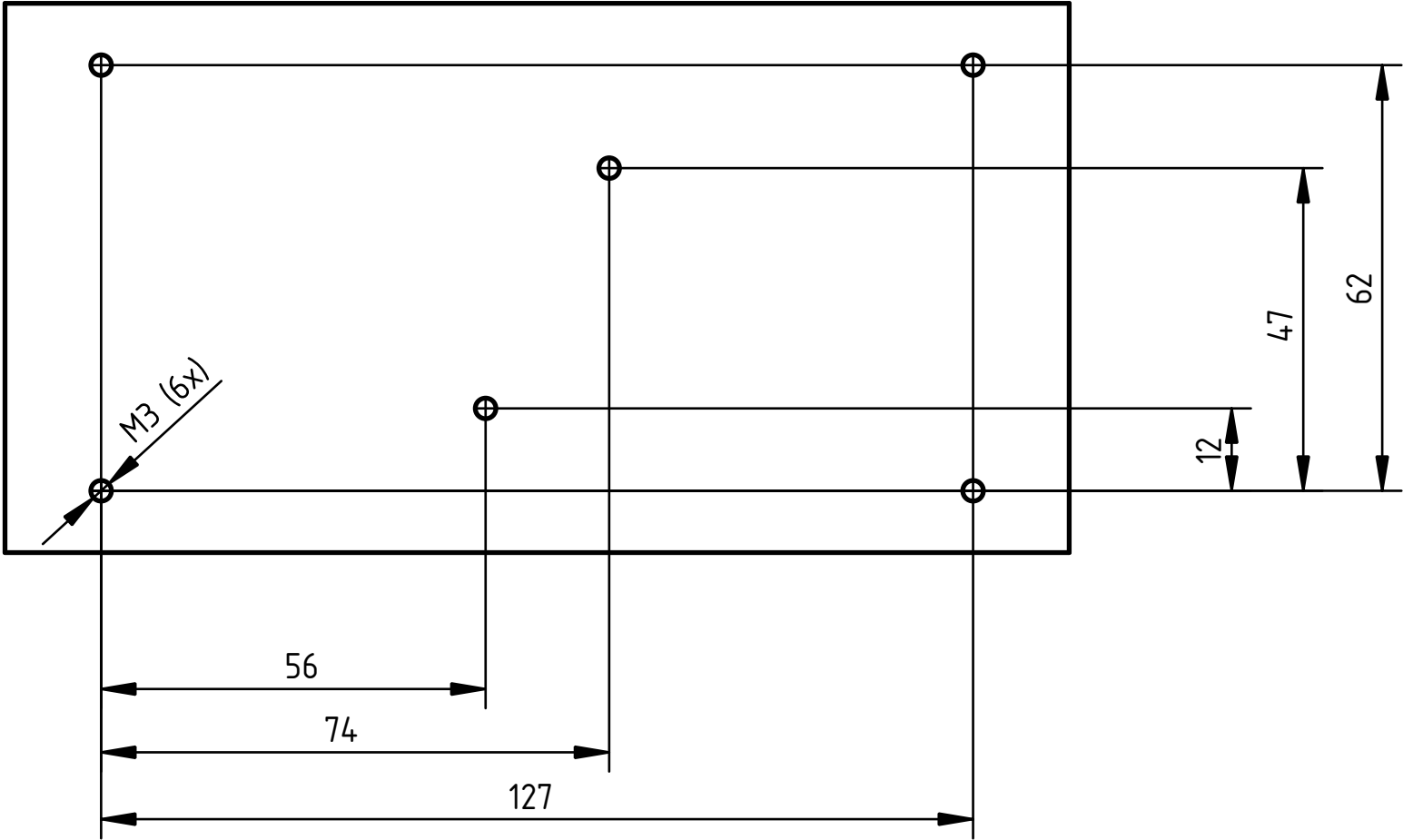
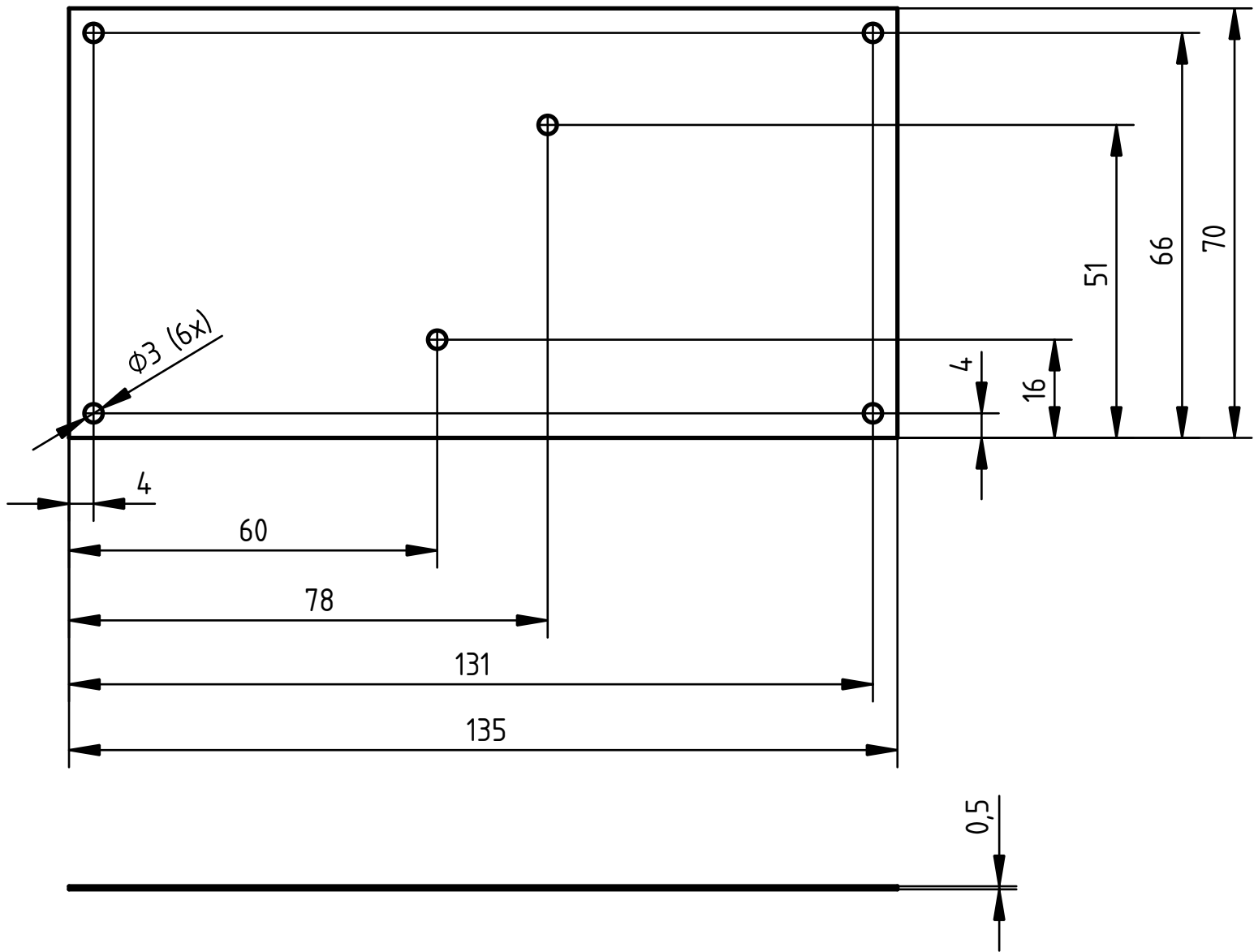


Back Plate / Heat Sink pattern



Thermal Pad



Notes:

Thermal pad and back plate only required for high current applications.

Assembly with stand-offs sufficient for low current applications.

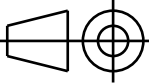
Thermal requirements depend on expected ambient temperature, continuous current and selected parts on PCB (especially MOSFETs).

Thermal Pad material recommendation


- Thickness: 0.5 mm
- Heat conductivity: >1 W/mK
- Electrically isolating
- Example: Bergquist GAP PAD A2000

If not stated otherwise, general tolerances according to ISO 2768-mK apply.

Scale 1:1



All dimensions in mm

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